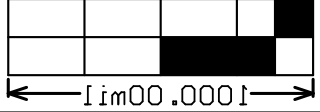
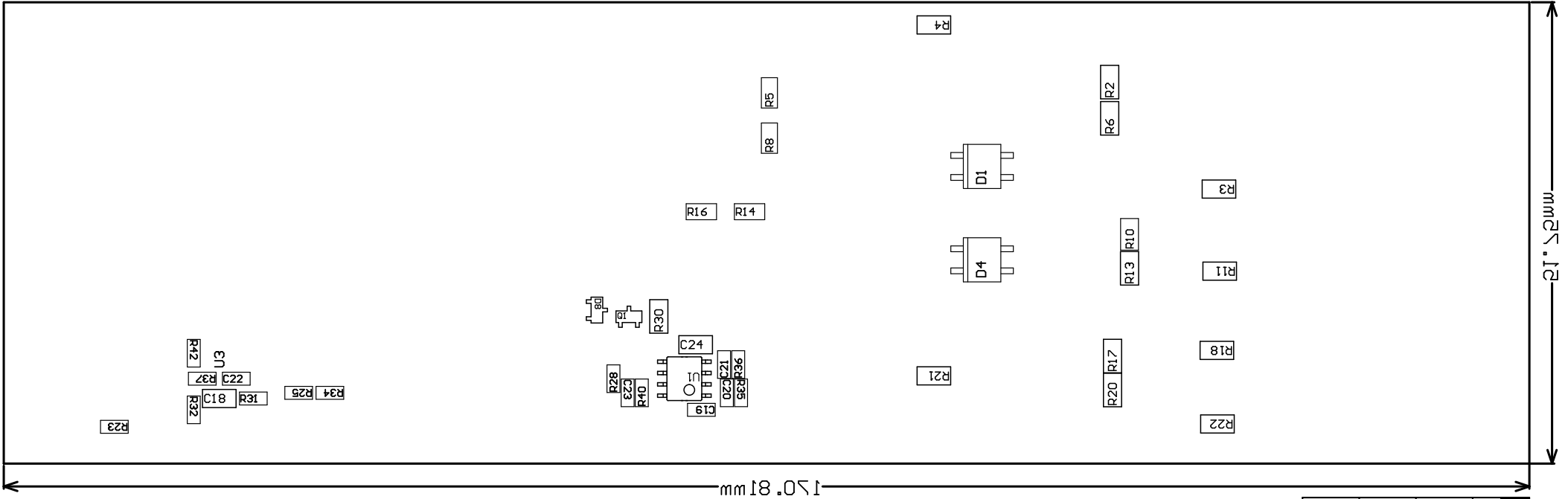


PCB VIEWED FROM TOP SIDE	BOARD #: PMP30094	REV: A	SUN REV: Not In VersionControl
M2 Board Dimensions	TID #: ChangeMe!		
PLOT NAME = Assembly Top	GENERATED : 12/16/2016 11:20:02 AM		TEXAS INSTRUMENTS



PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30094	REV: A	SUN REV: Not In VersionControl
	TID #: ChangeMe!	MS Board 07/16/2016 11:20:03 AM	
PLOT NAME = Assembly Bottom	GENERATED : 12/16/2016 11:20:03 AM	TEXAS INSTRUMENTS	

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